1. INTRODUCTION

- This specification covers the requirements for USB B 4POS SMT series.

  Include 1734517 Series, total 3 P/N, See table 1.

W/O	WHITE	1734517-3
W/	BLACK	1734517-2
W/O	BLACK	1734517-1
MYLAR	COLOR	PART NUMBER

table 1

- Product include Shell,Housing,Terminal, See Figure 1.

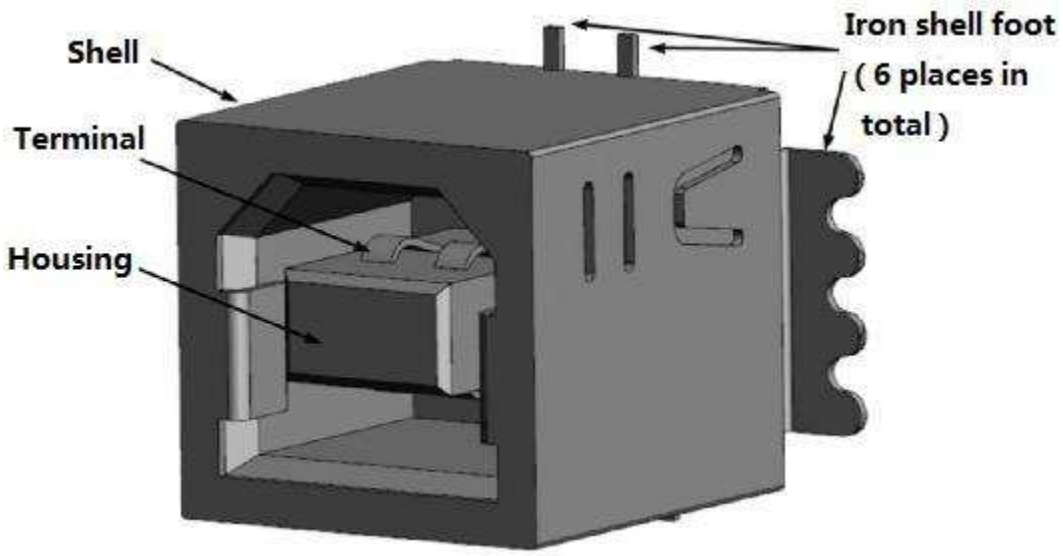

Figure 1

2.REFERENCE MATERIAL

2.1 Revision Summary

- Initial release

2.2 Customer Assistance

- A service network established can help you obtain product and tooling information which can be obtained through a local TE Representative or, after purchase, by calling the Product Information Center at the number at the bottom.

2.3 Drawings

- Customer Drawings for product part numbers are available from the service network. If there is a conflict between the information contained in the Customer Drawings and this specification or with any other technical documentation supplied, the Customer Drawing takes preference.

2.4 Related Specifications

- 108-57538 Product Specification
- 501-57618 Qualification Test Report of High Speed 05FH

3. REQUIREMENTS

3.1 Storage

(A). This connector is packaged and shipped in an emboss tape, tube or hard tray. We recommend that the connector remain in the container to prevent contamination or dust, and it is stored, keeping at normal temperatures, normal humidity and no poisonous gas.

(Normal temperatures and humidity: 5~35℃, 45~75% RH)

(B). If this connector is stored in the middle of operating, it should not remain naked.

(C). We recommend that this connector isn't stored for a long time after opening a package and that it is used within three months.

3.2 Printed Circuit Board

The PC board shall be glass epoxy. If a thin board is used, we recommend you to give support to it from reverse side in order to prevent bowing of board during mating.

3.3 PC Board Layout

- Please refer to customer drawing.

3.4 Solder Techniques

(A) Recommend Solder Paste

1. Alloy type shall be SAC 405 for lead-free application.
2. Flux shall be RMA type.

(B) Stencil

Stencil aperture will be determined by the thickness of the stencil being used. Generally, the thinner stencils will have a larger aperture to maintain a given volume of solder paste. Solder deposition should be within the pad area of the contact solder tines. The recommended thickness of stencil: 0.12~0.15mm.

(C) Solder Mask

Solder mask is recommended between all pads. If a trace is run between adjacent pads on the solder side of the pc board, a solder mask must be applied over the trace to prevent bridging and wicking of solder away from the contact solder tines. Liquid photo imageable or dry film solder masks are recommended. The recommended thickness of mask: 0.01~0.05mm.

(D) Reflow Condition

For lead-free application:

Refer to IPC/JEDEC J-STD-020.

Preheat: 150~200℃ 60~180 Sec.

Heat: 217℃Min 60~150 Sec.

Heat peak: 260℃Max

(E) Connector Placement

Connectors can be placed on the pc board by hand or manipulator.

(F) Repair

If a soldering iron is used, full care must be taken not to contact the solder tine by tip of a soldering iron.

Recommended temperature of soldering iron: 300℃Max

Operating time: 3 Sec. Max. per pad.

3.5 Mating and Un-mating Connector

- mating and un-mating distance 2.67 mm minimum,See Figure 2.

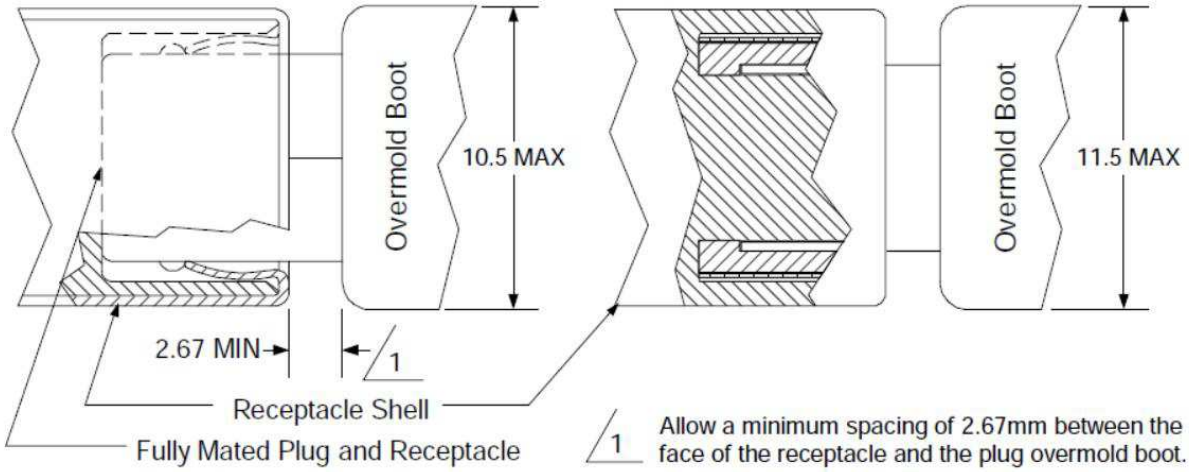

Figure 2